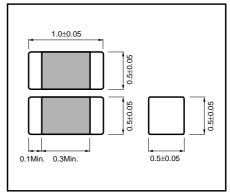
# Multi-layer ceramic chip capacitors

# MCH15 (1005 (0402) size, chip capacitor)

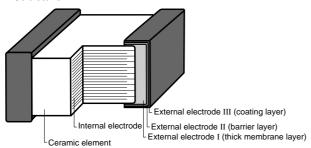
#### Features

- 1) Small size (1.0 x 0.5 x 0.5 mm) makes it perfect for lightweight portable devices.
- 2) Comes packed either in tape to enable automatic mounting or in bulk cases.
- 3) Precise uniformity of shape and dimensions facilitates highly efficient automatic mounting.
- 4) Barrier layer and end terminations to improve solderability.

#### ●External dimensions (Units : mm)



#### Structure

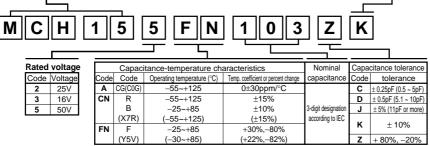


# Product designation

Code	Product thickness	Packaging specifications	Reel	Basic ordening unit (pcs.)
K	0.5mm	Paper tape (width 8 mm, pitch 2 mm)	φ180mm (7in.)	10,000
L	0.5mm	Paper tape (width 8 mm, pitch 2 mm)	ф330mm (13in.)	50,000
С	0.5mm	Bulk case	_	50,000

Reel (\$\phi180\$, \$\phi330mm\$): compatible with EIAJ ET-7200A Bulk case: compatible with EIAJ ET-7201A

No. Packaging style



<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

#### Capacitance range

For thermal compensation

Part n	MCH15	
Capacitance (pF)	Temperature characteristics	(CG) (C0G)
o ap across o (pr )	Rated voltage (V) Tolerance	50V
0.5 0.75 1		
1.1 1.2 1.3		
1.5 1.6 1.8		
2 2.2 2.4	C (± 0.25pF)	
2.7 3 3.3		
3.6 3.9 4		
4.3 4.7 5		
5.1 5.6 6		
6.2 6.8 7	D ( ± 0.5pF)	
7.5 8 8.2		
9 9.1 10		
11 12 13		
15 16 18		
20 22 24	J ( ± 5%)	
27 30 33		
36 39 43		

Part n	MCH15	
Capacitance (pF)	Temperature characteristics	A (CG) (C0G)
Capacitance (pr.)	Rated voltage (V) Tolerance	50V
47		
51 56		
62 68		
75		
82		
91		
100		
110		
120 130		
150	J ( ± 5%)	
160		
180		
200		
220		
240		
270		
300 330		
360		
390		
430		
470		
510		
560		

Product thickness (mm) 0.5 ± 0.05

<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

High dielectric constant

nigh delectric constant						
Part number		MCH15				
Capacitance (pF)	Temperature characteristics	CN (R) (B) (X7R)		FN (F) (Y5V)		
Capacitance (pr)	Rated voltage (V)	50V	16V	50V	25V	16V
	Tolerance	K ( ±10%)		Z (+80, -20%)		
220 270 330						
390 470 560						
680 820 1,000						
1,200 1,500 1,800						
2,200 2,700 3,300						
3,900 4,700 5,600						
6,800 8,200 10,000 (0.01μF)						
12,000 15,000 18,000						
22,000 27,000 33,000						
39,000 47,000 56,000						
68,000 82,000 100,000 (0.1μF)						
120,000 150,000 180,000						
220,000 270,000 330,000						
390,000 470,000 560,000						

Product thickness (mm)  $0.5\pm0.05$ 

<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

#### Characteristics

Class 1 (For thermal compensation)

	Temperature characteristics			
Item		A (CG) (C0G)	Test methods/conditions (based on JIS C 5102)	
Operating temperature		−55°C ~ 125°C		
Nominal capacitance (C)		Must be within the specified tolerance range.	Based on paragraph 7.8 and paragraph 9 Measured at room temperature and standard humidity,	
Dissipation factor (tanδ)		100/(400+20C)% or less: Less than 30 pF 0.1% or less : 30 pF or larger	1000pF or less Measurement frequency: 1 ± 0.1MHz  Measurement voltage: 1 ± 0.1Vrms.  Over 1000pF Measurement frequency: 1 ± 0.1kHz  Measurement voltage: 1 ± 0.1Vrms.	
Insulation resistance (IR)		10,000M $\Omega$ or 500M $\Omega \cdot \mu F$ , whichever is smaller	Based on paragraph 7.6 Measurement is made after rated voltage is applied for 60 ±	
Withstanding voltage		The insulation must not be damaged.	Based on paragraph 7.1 Apply 300% of the rated voltage for 1 to 5s then measure.	
Temperature ch	haracteristics	Within 0 ± 30ppm/°C	The temperature coefficients in table 12, paragraph 7.12 are calculated at 20°C and high temperature.	
Terminal adherence		No detachment or signs of detachment.	Based on paragraph 8.11. 2.  Apply 5N for 10 ± 1s in the direction indicated by the arrow.  Pressure (5)  Capacitor	
	Appearance	There must be no mechanical damage.	Chip is mounted to a board in the manner	
Resistance to vibration	Rate of capacitance change	Must be within initial tolerance.	shown on the right, subjected to vibration (type A in paragraph 8.2), and measured	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	24 ± 2 hrs. later.	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.	Based on paragraph 8.13 Soldering temperature: $235 \pm 5$ °C Soldering time : $2 \pm 0.5$ s	
	Appearance	There must be no mechanical damage.		
	Rate of capacitance change	$\pm$ 2.5% or $\pm$ 0.25 pF, whichever is larger.	Based on paragraph 8.14.	
Resistance to soldering	Dissipation factor (tanδ)	Must satisfy initial specified value.	Soldering temperature: 260 ± 5°C	
heat	Insulation resistance	10,000M $\Omega$ or 500M $\Omega \cdot \mu F$ , whichever is smaller	Soldering time : $5 \pm 0.5s$ Preheating : $150 \pm 10^{\circ}$ C for 1 to 2 min.	
	Withstanding voltage	The insulation must not be damaged.		
	Appearance	There must be no mechanical damage.		
_	Rate of capacitance change	$\pm$ 2.5% or $\pm$ 0.25 pF, whichever is larger.	Based on paragraph 9.3	
Temperature cycling	Dissipation factor (tanδ)	Must satisfy initial specified value.	Number of cycles : 5	
	Insulation resistance	10,000M $\Omega$ or 500M $\Omega \cdot \mu F,$ whichever is smaller	Capacitance measured after 24 ± 2 hrs.	
	Appearance	There must be no mechanical damage.	Based on paragraph 9.9	
Humidity load test	Rate of capacitance change	$\pm$ 7.5% or $\pm$ 0.75 pF, whichever is larger.	Test temperature: 40 ± 2°C Relative humidity: 90% to 95%	
	Dissipation factor (tanδ)	0.5% or less	Applied voltage : rated voltage	
	Insulation resistance	500M $\Omega$ or 25M $\Omega \cdot \mu F$ , whichever is smaller	Test time : 500 to 524 hrs. Capacitance measured after 24 ± 2 hrs.	
	Appearance	There must be no mechanical damage.	Based on paragraph 9.10	
High- temperature load test	Rate of capacitance change	$\pm3.0\%$ or $\pm0.3$ pF, whichever is larger.	Test temperature: Max. operating temp.	
	Dissipation factor (tanδ)	0.3% or less	Applied voltage : rated voltage × 200% Test time : 1,000 to 1,048 hrs.	
	Insulation resistance	1,000M $\Omega$ or 50M $\Omega \cdot \mu F$ , whichever is smaller	Capacitance measured after 24 ± 2 hrs.	

<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.



#### Class 2 (High dielectric constant)

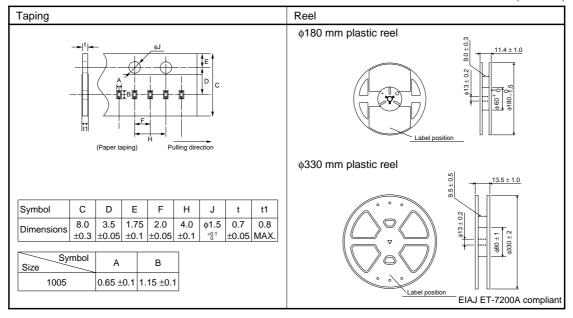
	lectric constant)	I			
Temperature characteristics		CN (R) (B) (X7R)	FN (F) (Y5V)	Test methods/conditions (based on JIS C 5102)	
Operating temperature		−55°C ~ +125°C	−30°C ~ +85°C		
Nominal capacitance (C)		Must be within the specified tolerance range.		Measurement voltage :1.0 ± 0.2 Vrms.	
Dissipation factor (tanδ)		2.5% or less 5.0% or less when rated voltage is 16V: 3.5% or less) (when rated voltage is 16V: 7.5% or less)			
Insulation resistance (IR)		10,000M $\Omega$ or 500M $\Omega$ · μF, whichever is smaller		Based on paragraph 7.6 Measurement is made after rated voltage is applied for 60 ± 5s.	
Withstanding voltage		The insulation must not be damaged.		Based on paragraph 7.1 Apply 250% of the rated voltage for 1 to 5s then measure	
Temperature characteristics		Within ± 15%	+ 22, + 82%	The temperature coefficients in paragraph 7.12, table 8, condition B, are based on measurements carried out at 20°C, with no voltage applied.	
Terminal adherence		No detachment or signs of detachment		Based on paragraph 8. 11. 2. Apply SN for $10 \pm 1s$ in the direction indicated by the arrow. Pressure (5 capacitor	
	Appearance	There must be no mechanical damage.		Chip is mounted to a board in the manner shown on the right, subjected to vibration (type A in paragraph 8.2),	
Resistance to vibration	Rate of capacitance change	Must be within initial tolerance.			
	Dissipation factor (tanδ)	Must satisfy initial specified value.		and measured 48 ± 4 hrs. later. Board	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.		Based on paragraph 8. 13 Soldering temperature : 235 $\pm$ 5°C Soldering time : 2 $\pm$ 0.5s	
	Appearance	There must be no mechanical damage.			
	Rate of capacitance change	Within ± 5.0% Within ± 20.0%		Based on paragraph 8.14. Soldering temperature: 260 ± 5°C	
Resistance to soldering	Dissipation factor (tanδ)	Must satisfy initial specified value.			
heat	Insulation resistance	10,000Μ $\Omega$ or 500Μ $\Omega \cdot \mu F$ , whichever is smaller		Soldering time $: 5 \pm 0.5s$ Preheating $: 150 \pm 10^{\circ}\text{C}$ for $: 1 \text{ to 2 min.}$	
	Withstanding voltage	The insulation must not be damaged.			
	Appearance	There must be no mechanical damage.			
Temperature	Rate of capacitance change	Within ± 7.5%	Within ± 20.0%	Based on paragraph 9.3 Number of cycles : 5	
cycling	Dissipation factor (tanδ)	Must satisfy initial specified value.		Capacitance measured after $48 \pm 4 \text{ h}$	
	Insulation resistance	10,000M $\Omega$ or 500M $\Omega$ · μF, whichever is smaller			
Humidity load test	Appearance	There must be no n	nechanical damage.	Based on paragraph 9.9	
	Rate of capacitance change	± 12.5% or less	Within ± 30.0%	Test temperature: 40 ± 2°C	
	Dissipation factor (tanδ)	5.0% or less	7.5% or less (when rated voltage is 16V: 10.0%)	Relative humidity: 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs.	
	Insulation resistance	500MΩ or 25MΩ $\cdot$ μF, whichever is smaller		Capacitance measured after 48 ±	
High- temperature load test	Appearance	There must be no mechanical damage.			
	Rate of capacitance change	Within ± 10.0%	Within ± 30.0%	Based on paragraph 9.10	
	Dissipation factor (tanδ)	5.0% or less	7.5% or less (when rated voltage is 16V: 10.0%)	Test temperature: Max. operating tem Applied voltage : rated voltage × 200 Test time : 1,000 to 1,048 hrs.	
	Insulation resistance	1,000M $\Omega$ or 50M $\Omega$ · μF, whichever is smaller		Capacitance measured after 48 ± 4 l	

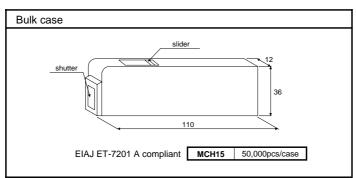
<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.



### Packaging specifications

(Units : mm)





<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

#### Electrical characteristics

#### ■ A (C0G) Characteristics

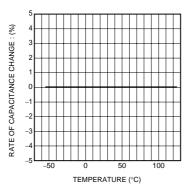


Fig.1 Capacitance-temperature characteristics

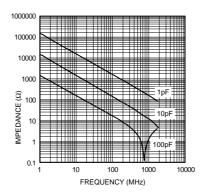


Fig.2 Impedance-frequency characteristics

# ■ CN (X7R) Characteristics

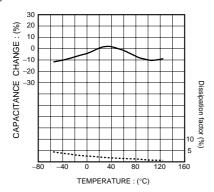


Fig.3 Capacitance-temperature characteristics

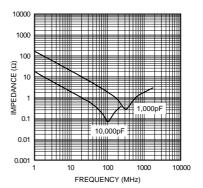


Fig.4 Impedance-frequency characteristics

### ■FN (Y5V) Characteristics

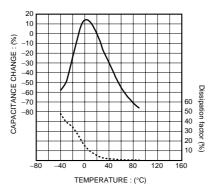


Fig.5 Capacitance-temperature characteristics

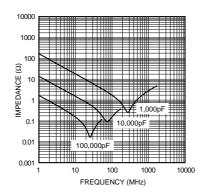
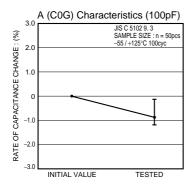


Fig.6 Impedance-frequency characteristics

<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

### ■ Temperature cycling test





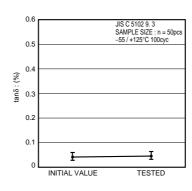


Fig.8 tanδ

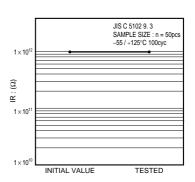


Fig.9 Insulation resistance

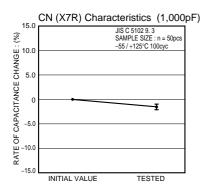


Fig.10 Rate of capacitance change

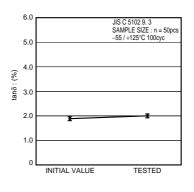


Fig.11  $tan\delta$ 

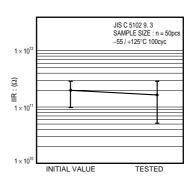


Fig.12 Insulation resistance

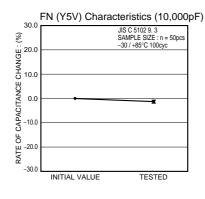


Fig.13 Rate of capacitance change

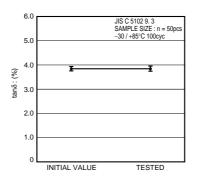


Fig.14 tanδ

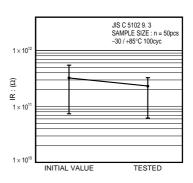
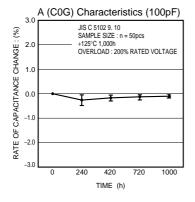
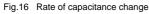


Fig.15 Insulation resistance

<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

#### ■ High-temperature load test





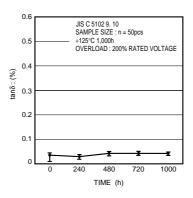


Fig.17  $tan\delta$ 

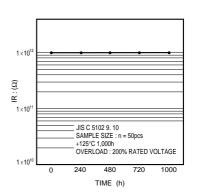


Fig.18 Insulation resistance

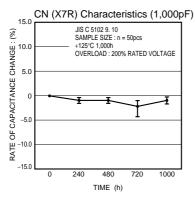


Fig.19 Rate of capacitance change

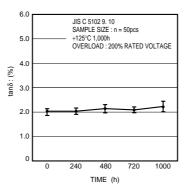


Fig.20 tanδ

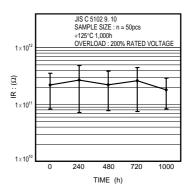


Fig.21 Insulation resistance

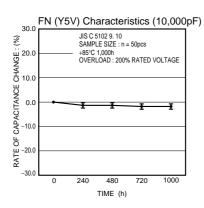


Fig.22 Rate of capacitance change

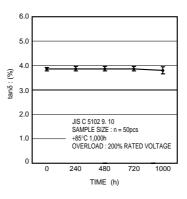


Fig.23  $tan\delta$ 

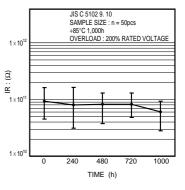


Fig.24 Insulation resistance

<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

# ■ Humidity load test

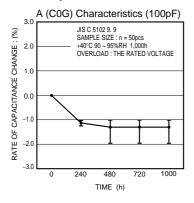


Fig.25 Rate of capacitance change

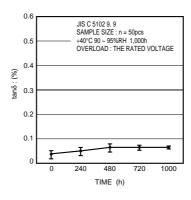


Fig.26 tanδ

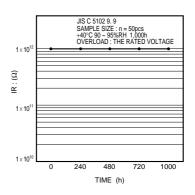


Fig.27 Insulation resistance

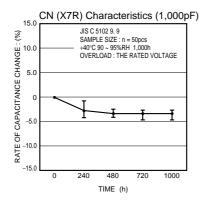


Fig.28 Rate of capacitance change

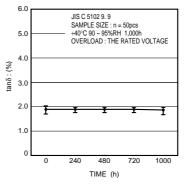


Fig.29 tanδ

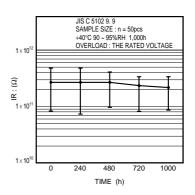


Fig.30 Insulation resistance

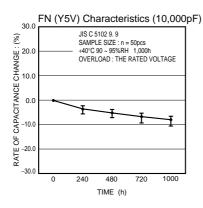


Fig.31 Rate of capacitance change

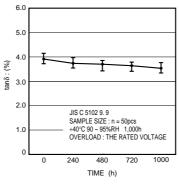


Fig.32  $tan\delta$ 

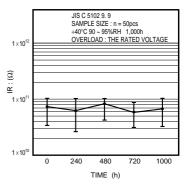


Fig.33 Insulation resistance

<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.